

ROHS G591

B±0.30

Pin1

7.8±0.25

2.00

A±0.25

SQ=0.50

2.00

ø0.80

RECOMMENDED PCB LAYOUT
(TOLERANCE:±0.10)

8.0

7.2

3.00±0.2

2.00

1.ELECTRICAL SPECIFICATIONS:

- 1.1 Rated current and voltage(额定电流):
3.0A 250V AC(r.m.s)
- 1.2 Dielectric Withstanding Voltage(耐电压) :
800V AC for one minute
- 1.3 Contact Resistance(接触电阻) :
20mΩ max
- 1.4 Insulation Resistance(绝缘电阻) :
1000MΩ min
- 1.5 Operating Temperature(工作温度) :
-25℃ ~ 85℃

2.MATERIAL SPECIFICATION:

- 2.1 Insulator Material(绝缘体材质):
PA46 UL94V-0
- 2.2 Contact Material(端子材质):
Brass,Tin Plated

PART NO. LEGEND:
WB2013DS-XXT3C-P

Insulator Material: 3:PA46

Contact Plating :T:Tin all Over

NO of Contacts: 4 to 40

Welding Method:DS=DIP180°

Wafer Conn

▲ Non-tooled parts No.of positions DIM list:

CONTACTS	DIMENSIONS	
	A	B
4	2.00	6.00
6	4.00	8.00
8	6.00	10.00
10	8.00	12.00
12	10.00	14.00
14	12.00	16.00
16	14.00	18.00
18	16.00	20.00
20	18.00	22.00
22	20.00	24.00
24	22.00	26.00
26	24.00	28.00
28	26.00	30.00
30	28.00	32.00
32	30.00	34.00
34	32.00	36.00
36	34.00	38.00
38	36.00	40.00
40	38.00	42.00

DRAWING:
Hu yatao

CHECKED:
Tony

APPROVAL:
Yang jie

GENERAL TOLERANCE

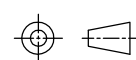
.X:=±0.30 .X*:=±2°
.XX:=±0.25 .XX*:=±1°
.XXX:=±0.15 .XXX*:=±0.5°

UNIT: MM

SCALE: N/A

SHEET: 1/1

PROJECTION:



CHIN-BAN
electronics (H.K.) co., ltd

DESCRIPTION:
2.00mm Wire To Board Wafer Double Row 180°

PART NO: WB2013DS-XXT3C-P REV: 1.0

CUSTOMER NO: SIZE: A4